

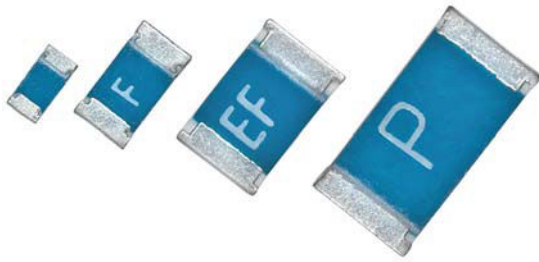


**THE DATASHEET OF
MFU0805FF03000P100**





Thin Film Chip Fuses



MFU Thin Film Chip Fuses are the perfect choice for the most fields of modern electronics. The highly controlled manufacturing thin film process guarantees an outstanding stability of fusing characteristics. Typical applications include information technology, telecommunication, medical equipment, industrial, audio/video, and automotive electronics.

FEATURES

- Advanced thin film technology
- Very quick acting fuse characteristics
- Outstanding stability of fusing characteristics
- Green product, supports lead (Pb)-free soldering
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Information technology
- Industrial electronics
- Automotive electronics
- Telecommunication
- Medical equipment
- Audio/video electronics

SIZE				
INCH	0402	0603	0805	1206
METRIC	1005M	1608M	2012M	3216M

TECHNICAL SPECIFICATIONS				
DESCRIPTION	MFU 0402	MFU 0603	MFU 0805	MFU 1206
Metric size	1005M	1608M	2012M	3216M
Rated current range I_R	0.5 A to 3.15 A	0.5 A to 5.0 A	0.5 A to 5.0 A	0.5 A to 6.3 A
Rated voltage, U_{max} . DC	32 V	32 V	32 V	63 V
Breaking Capacity, I_{max} . at U_{max} . DC	50 A at 32 V	50 A at 32 V	50 A at 32 V	50 A at 63 V
Voltage drop at $1 \times I_R$	90 mV to 368 mV	85 mV to 361 mV	98 mV to 374 mV	116 mV to 433 mV
Cold resistance at $0.1 \times I_R$	22 mΩ to 560 mΩ	13 mΩ to 550 mΩ	15 mΩ to 570 mΩ	14 mΩ to 660 mΩ
Permissible film temperature, $\vartheta_{F max}$.	125 °C			
Operating temperature range	- 55 °C to 125 °C			
Permissible continuous current rating at $\vartheta_{amb} = 23$ °C	0.7 x I_R			
Approval UL recognition file	E253806			
Approval IEC 60127-4	n/a	Refer to table: MFU 0603 RATING		Refer to table: MFU 1206 RATING
FIT _{observed}	$\leq 0.2 \times 10^{-9}/h$			



PART NUMBER AND PRODUCT DESCRIPTION (1)

Part Number: MFU0603FF01000PW00

M	F	U	0	6	0	3	F	F	0	1	0	0	0	P	W	0	0
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MODEL/SIZE	FUSING CHARACTERISTIC	RATED CURRENT	PACKAGING (2)	SPECIAL
MFU0402 MFU0603 MFU0805 MFU1206	FF = Very quick acting	Examples: 0.5 A = 00500 1.0 A = 01000 6.3 A = 06300	E1 E5 E0 P1 P5 PW	Up to 2 digits 00 = Standard

Product Description: MFU 0603 -FF PW 1A0

MFU	0603	-FF	PW	1A0
MODEL	SIZE	FUSING CHARACTERISTIC	PACKAGING (2)	RATED CURRENT
MFU	0402 0603 0805 1206	FF = Very quick acting	E1 E5 E0 P1 P5 PW	Examples: 0.5 A = 0A5 1.0 A = 1A0 6.3 A = 6A3

Notes

- (1) Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION
- (2) Please refer to table PACKAGING

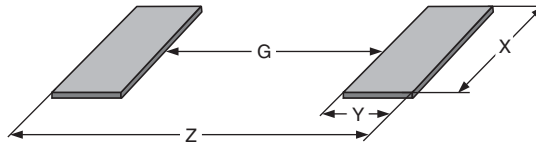
PACKAGING						
TYPE	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER
MFU 0402	E1	1000	Card board tape acc. IEC 60286-3 Type I	8.0	2.0	180 mm/7"
	E5	5000				
	E0	10 000				
MFU 0603	P1	1000			4.0	180 mm/7"
	P5	5000				
	PW	20 000				
MFU 0805	P1	1000		330 mm/13"		
	P5	5000				
	PW	20 000				
MFU 1206	P1	1000		180 mm/7"		
	P5	5000				
	PW	20 000				
						330 mm/13"

DIMENSIONS



DIMENSIONS - Chip fuse types, mass and relevant physical dimensions							
TYPE	H (mm)	L (mm)	W (mm)	W _T (mm)	T ₁ (mm)	T ₂ (mm)	MASS (mg)
MFU 0402	0.32 ± 0.07	1.0 ± 0.05	0.5 ± 0.05	> 75 % of W	0.2 + 0.1/- 0.15	0.2 ± 0.1	0.65
MFU 0603	0.45 + 0.1/- 0.05	1.55 ± 0.05	0.85 ± 0.1	> 75 % of W	0.3 + 0.15/- 0.2	0.3 + 0.15/- 0.2	1.9
MFU 0805	0.45 + 0.1/- 0.05	2.0 ± 0.1	1.25 ± 0.15	> 75 % of W	0.4 + 0.1/- 0.2	0.4 + 0.1/- 0.2	4.7
MFU 1206	0.55 ± 0.1	3.2 + 0.1/- 0.2	1.6 ± 0.15	> 75 % of W	0.5 ± 0.25	0.5 ± 0.25	9.5

SOLDER PAD DIMENSIONS



RECOMMENDED SOLDER PAD DIMENSIONS								
TYPE	WAVE SOLDERING				REFLOW SOLDERING			
	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)
MFU 0402	-	-	-	-	0.35	0.55	0.55	1.45
MFU 0603	0.55	1.10	1.10	2.75	0.65	0.70	0.95	2.05
MFU 0805	0.80	1.25	1.50	3.30	0.90	0.90	1.40	2.70
MFU 1206	1.40	1.50	1.90	4.40	1.50	1.15	1.75	3.80

Note

- The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters.

DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade ceramic body. The fuse elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure performed on 100 % of the individual fuses. Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3**.

APPROVALS

The fuses are tested in accordance with the following standards:

- IEC 60127-1
- IEC 60127-4
- UL 248-14
- IEC 60068 series

Approval of conformity is indicated by the UMF Logo on the package label. Recognition by Underwriter Laboratories Inc. is indicated by the UL logo on the package label.

ASSEMBLY

The fuses are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapour phase. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The fuses are RoHS compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The immunity of the plating against tin whisker growth has been proven under extensive testing. Solderability is specified for 2 years after production or re-qualification. The permitted storage time is 20 years.

All products comply with the **JIG 101** list of legal restrictions on hazardous substances.

This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the use of Hazardous Substances Directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

FUNCTIONAL PERFORMANCE



Current Rating Factor (1) vs. Ambient Temperature θ_{amb}

Note

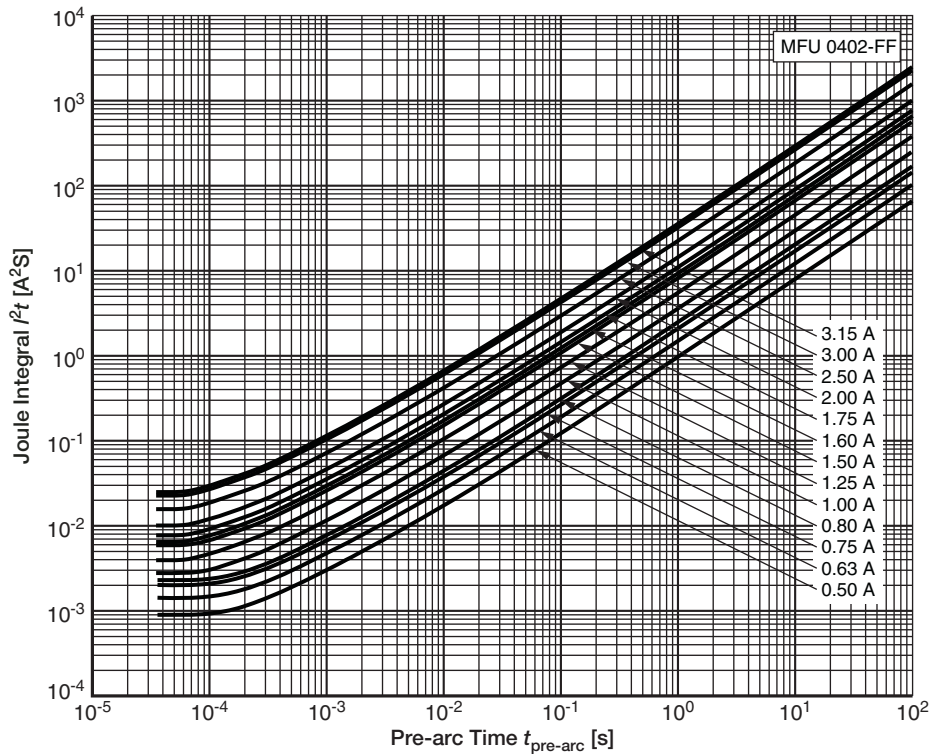
(1) Current rating factor is in addition to the given permissible continuous current rating of 0.7



FUNCTIONAL PERFORMANCE



Typical $t_{pre-arc}$ vs. I characteristic of MFU 0402 ⁽¹⁾



Typical I^2t vs. $t_{pre-arc}$ characteristic of MFU 0402 ⁽¹⁾

Note

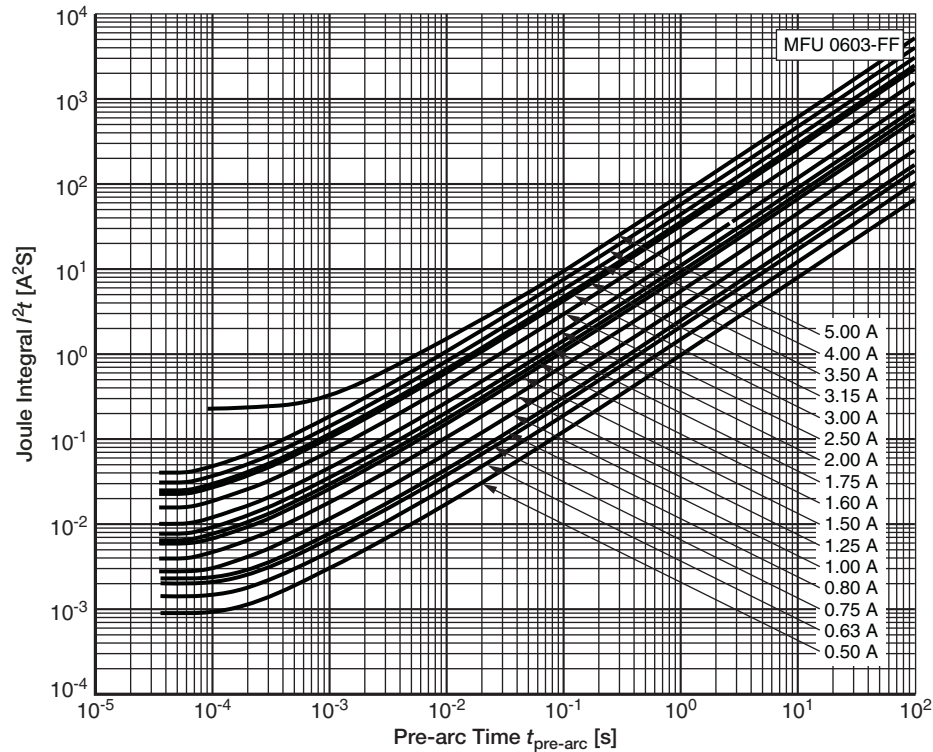
⁽¹⁾ Fuses mounted on a test board according to IEC 60127-4



FUNCTIONAL PERFORMANCE



Typical $t_{pre-arc}$ vs. I characteristic of MFU 0603 ⁽¹⁾



Typical I^2t vs. $t_{pre-arc}$ characteristic of MFU 0603 ⁽¹⁾

Note

⁽¹⁾ Fuses mounted on a test board according to IEC 60127-4



FUNCTIONAL PERFORMANCE



Typical $t_{pre-arc}$ vs. I characteristic of MFU 0805 ⁽¹⁾

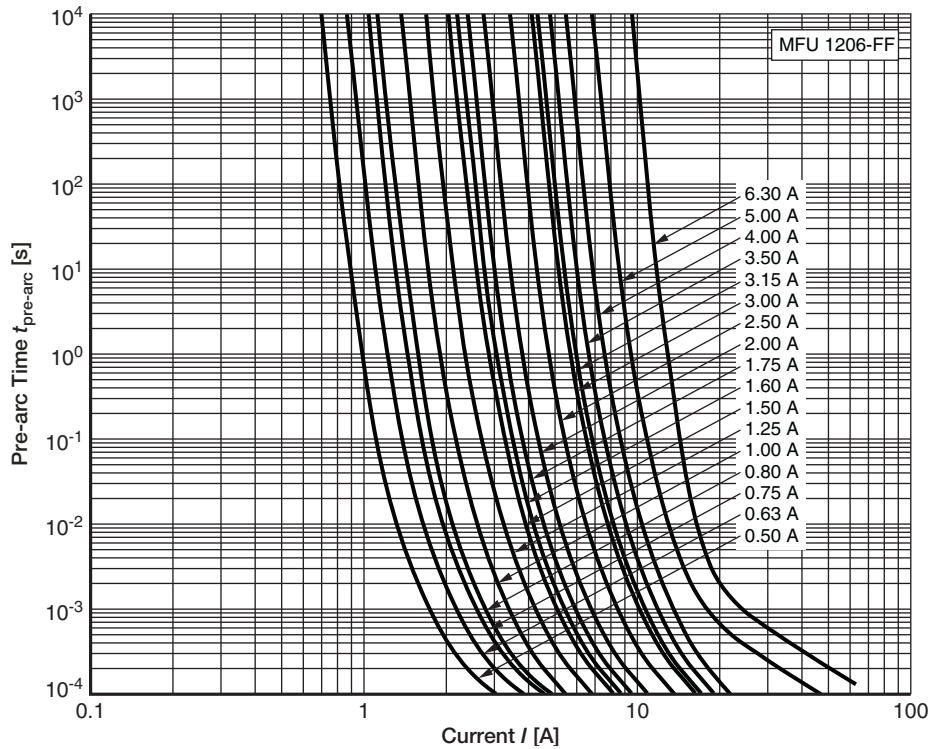


Typical I^2t vs. $t_{pre-arc}$ characteristic of MFU 0805 ⁽¹⁾

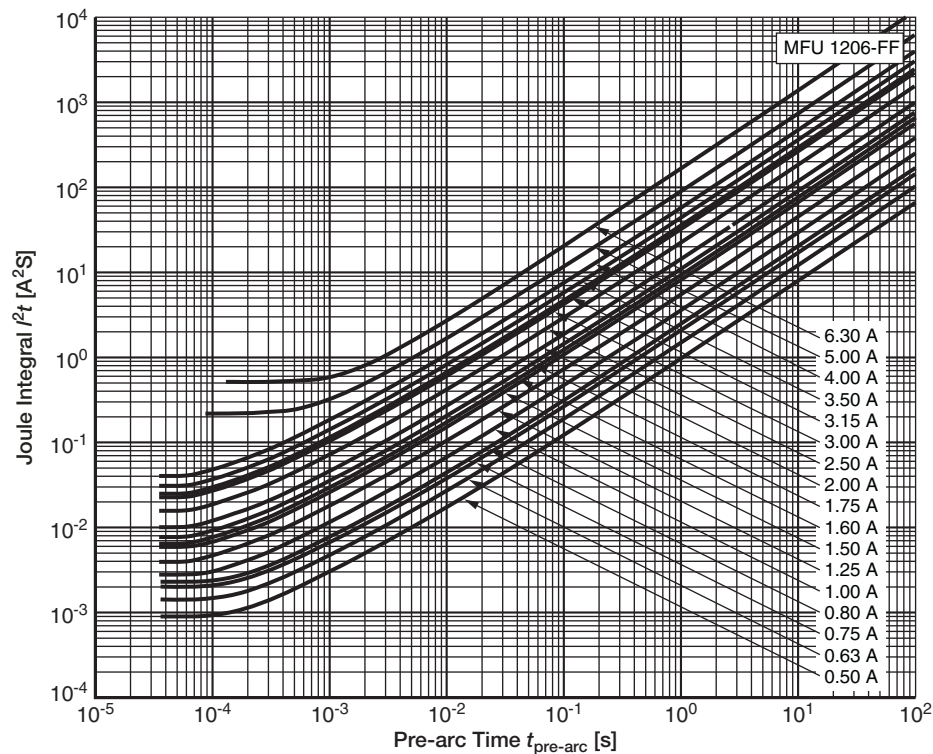
Note

⁽¹⁾ Fuses mounted on a test board according to IEC 60127-4

FUNCTIONAL PERFORMANCE



Typical $t_{pre-arc}$ vs. I characteristic of MFU 1206 ⁽¹⁾



Typical I^2t vs. $t_{pre-arc}$ characteristic of MFU 1206 ⁽¹⁾

Note

⁽¹⁾ Fuses mounted on a test board according to IEC 60127-4



TEST AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

IEC 60127-1, Miniature fuse - Part 1: Definitions for miniature fuses and general requirements for miniature fuse-links

IEC 60127-4, Universal Modular Fuse Links (UMF)

UL 248-14, Low voltage fuses - Part 14: Supplemental fuses

For the full test schedule refer to the documents listed above. The testing also covers most of the requirements specified by METI and CCC.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 5.3. Climatic category LCT/UCT/56 (rated temperature range: Lower category temperature, upper category temperature; damp heat, long term, 56 days) is valid.

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C

Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

The components are mounted for testing on printed-circuit boards in accordance with IEC 60127-4, unless otherwise specified.

The requirements stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of IEC 60127-1 and IEC 60127-4 respectively. However, some additional tests and a number of improvements against those minimum requirements have been included.

TEST PROCEDURES AND REQUIREMENTS					
IEC 60127-4 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE		REQUIREMENTS PERMISSIBLE CHANGE
8.3.2	21 (U _{e1})	Substrate bending	Depth 1 mm; rate 1 mm/s 1 times		No visible damage $\Delta R/R \leq \pm 10 \%$
8.6.2	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux; (215 ± 3) °C; (3 ± 0.3) s		Good tinning ($\geq 95 \%$ covered); no visible damage
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux; (245 ± 3) °C; (2 ± 0.2) s		
8.7.2	58 (Td)	Resistance to soldering heat	Solder bath method; (260 ± 5) °C; (10 ± 1) s		No visible damage $\Delta R/R \leq \pm 10 \%$
			Reflow method 2 (IR/forced gas convection); (260 ± 5) °C; (10 ± 1) s		
9.2.1	-	Time/current characteristics at nominal temperature	Cold resistance at $0.1 \times I_R$; destructive testing under overcurrent conditions (DC-Current)	MFU 0402 $I_R \leq 0.75 \text{ A}$	At $1.25 \times I_R$, $t_{\text{pre-arc}} > 1 \text{ h}$ at $2.0 \times I_R$, $t_{\text{pre-arc}} < 60 \text{ s}$ at $10 \times I_R$, $t_{\text{pre-arc}} < 0.001 \text{ s}$
				MFU 0402 $0.8 \text{ A} \leq I_R \leq 3.15 \text{ A}$	
				MFU 0603 $I_R \leq 5.0 \text{ A}$	
				MFU 0805 $I_R \leq 5.0 \text{ A}$	
				MFU 1206 $I_R \leq 6.3 \text{ A}$	
9.3.2	-	Breaking capacity	50 A at rated voltage acc. to UL 248-14		Optical inspection with naked eye no visible damage
9.3.3	-	Residual resistance	50 A at rated voltage acc. to UL 248-14		Insulation resistance at $2.0 \times U_R$ (DC) higher than 0.1 M Ω



TEST PROCEDURES AND REQUIREMENTS						
IEC 60127-4 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE			REQUIREMENTS PERMISSIBLE CHANGE
9.4	-	Endurance test acc. to IEC 60127-1	a) $I = 1.0 \times I_R(\text{DC})$ 1.0 h on; 0.25 h off; 23 °C; 100 times b) $I = 1.25 \times I_R(\text{DC})$ 1.0 h on 23 °C; 1 time	MFU 0402 MFU 0603 MFU 0805 MFU 1206	$I_R \leq 3.15 \text{ A}$ $I_R \leq 3.15 \text{ A}$ $I_R \leq 3.15 \text{ A}$ $I_R \leq 3.15 \text{ A}$	No visible damage $\Delta R/R \leq \pm 10 \%$
9.5	-	Maximum sustained dissipation acc. to IEC 60127-1	Calculation in accordance with results of clause 9.4 b)			Dissipation \leq acc. to IEC 60127-4 table 2
9.7	-	Fuse-link temperature	The test is performed during the final 5 min of clause 9.4 b)	MFU 0402 MFU 0603 MFU 0805 MFU 1206	$I_R \leq 3.15 \text{ A}$ $I_R \leq 3.15 \text{ A}$ $I_R \leq 3.15 \text{ A}$ $I_R \leq 3.15 \text{ A}$	Temperature rise of terminals $\leq 85 \text{ K}$
-	-	Verification of temp.-rise and current-carrying capacity acc. to UL 248-14 clause 8.2.3	$I = 1.0 \times I_R(\text{DC})$	MFU 0402 MFU 0603 MFU 0805 MFU 1206	$I_R \leq 3.15 \text{ A}$ $I_R \leq 5.0 \text{ A}$ $I_R \leq 5.0 \text{ A}$ $I_R \leq 6.3 \text{ A}$	Temperature rise of hot spot $\leq 75 \text{ K}$ acc. to UL 248-14 clause 8.2.4
-	78 (Cab)	Damp heat, steady state	(40 \pm 2) °C; 56 days; (93 \pm 3) % RH			$\Delta R/R \leq \pm 10 \%$ I-t characteristic
-	14 (Na)	Rapid change of temperature	30 min at LCT; 30 min at UCT; LCT = - 55 °C; UCT = 125 °C; 5 cycles			$\Delta R/R \leq \pm 10 \%$
-	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude $\leq 1.5 \text{ mm}$ or $\leq 200 \text{ m/s}^2$; 6 h			$\Delta R/R \leq \pm 10 \%$
-	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 °C; method 2			No visible damage
-	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 °C; method 1, toothbrush			Marking legible, no visible damage
-	21 (Ue ₃)	Shear (adhesion)	RR 1608M; 9 N RR 2012M and RR 3216M; 45 N			No visible damage
-	-	Flammability	IEC 60695-2-2, needle flame test; 10 s			No burning after 30 s



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